CLAIMS

1. A system for positioning a wafer relative to a datum structure, the system comprising:

a camera arrangement including one or more cameras, each of the one or more cameras including a field of view when positioned in the camera arrangement, each field of view including a peripheral edge of the wafer and a peripheral edge of the datum structure;

a processor to receive positional data from the or each camera and determine, in relation to each field of view, a gap size between the respective peripheral edges of the wafer and the datum structure included in the respective field of view; and

a controller to adjust a position of the wafer relative to the datum structure based on the determined respective gap sizes,

wherein the controller includes a robotic arm of a vacuum transfer module (VTM), the robotic arm being adapted to move the one or more cameras between camera positions along the peripheral edges of the wafer and the datum structure to obtain respective fields of view of the camera positions.

2. The system of claim 1, wherein the datum structure includes an edge ring.

3. The system of claim 1, wherein the datum structure includes a chuck.

4. The system of claim 1, wherein the camera arrangement includes a further camera, the further camera providing positional data in relation to a respective further field of view, to the processor.

5. The system of claim 1, wherein the determined respective gap sizes are compared against respective predetermined gap sizes, the respective predetermined gap sizes associated with a centered or desired position of the wafer in relation to the datum structure.

6. The system of claim 1, wherein the processor identifies a center of the wafer based on the determined respective gap sizes.

7. The system of claim 1, wherein the one or more cameras include a single moveable camera.

8. The system of claim 7, wherein the single moveable camera is mounted on the robotic arm.

9. A method for positioning a wafer relative to a datum structure, the method comprising:

placing, adjacent a wafer processing chamber, a camera arrangement including one or more cameras, each of the one or more cameras including a field of view when positioned in the camera arrangement, each field of view including a peripheral edge of the wafer and a peripheral edge of the datum structure;

receiving positional data from the or each camera and determining, in relation to each field of view, a gap size between the respective peripheral edges of the wafer and the datum structure included in the respective field of view; and

adjusting, using a controller, a position of the wafer relative to the datum structure based on the determined respective gap sizes,

wherein the controller includes a robotic arm of a vacuum transfer module (VTM), the one or more cameras are mounted onto the robotic arm and the robotic arm is adapted to move the one or more cameras between camera positions along the peripheral edges of the wafer and the datum structure to obtain respective fields of view of the camera positions.

10. The method of claim 9, wherein the datum structure includes an edge ring.

11. The method of claim 9, wherein the datum structure includes a chuck.

12. The method of claim 9, further comprising including a further camera in the camera arrangement, and providing positional data from the

further camera, in relation to a respective further field of view, to the processor.

13. The method of claim 9, further comprising comparing the determined respective gap sizes against respective predetermined gap sizes, the respective predetermined gap sizes associated with a centered or desired position of the wafer in relation to the datum structure or the wafer processing chamber.

14. The method of claim 9, further comprising identifying a center of the wafer based on the determined respective gap sizes.

15. The method of claim 9, wherein the one or more cameras include a single moveable camera.

16. The method of claim 15, wherein the single moveable camera is mounted on the robotic arm.